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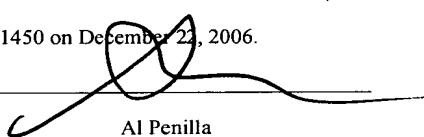
IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the application of:)
CHEN et al.) Group Art Unit: 3744
Application No: 10/712,708) Examiner: Ceric, L.
Filed: November 12, 2003) Docket No:JLINP174/TLC
For: HEAT DISSIPATION MODULE) Date: December 22, 2006
)

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, Alexandria, VA 22313-1450 on December 22, 2006.

Signed: _____


Al Penilla

Honorable Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

In response to the Office Action dated October 6, 2006, the term to respond extends to January 8, 2007. Please enter this amendment and remarks.

Amendments to the Specification begin on page 2 of this paper.

Amendments to the claims are reflected in the listing of claims which begin on page 6 of this paper.

Remarks/Arguments begin on page 10 of this paper.